



## Product Change Notification: CENO-27KSCM101

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### Date:

08-Oct-2026

### Product Category:

Pcie

### Notification Subject:

CCB 8193 Initial Notice: Qualification of STAK as an additional assembly site and bumping site for PCI1003/5CW, PCI1001/5CW, PCI1005/5CW, PCI1004/5CW, PCI1003-I/5CW, PCI1001-I/5CW, PCI1005-I/5CW, PCI1004-I/5CW, PCI1003T/5CW, PCI1001T/5CW, PCI1005T/5CW, PCI1004T/5CW, PCI1003T-I/5CW, PCI1001T-I/5CW, PCI1005T-I/5CW, PCI1004T-I/5CW, PCI1008-I/5CW, PCI1008T-I/5CW, PCI1003-V/5CWVAO, PCI1004-V/5CWVAO, PCI1003T-V/5CWVAO and PCI1004T-V/5CWVAO catalog part numbers (CPN) available in 353L FCCSP (16x16mm) package.

### Affected CPNs:

[CENO-27KSCM101\\_Affected\\_CPN\\_10082026.pdf](#)

[CENO-27KSCM101\\_Affected\\_CPN\\_10082026.csv](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of STAK as an additional assembly site and bumping site for PCI1003/5CW, PCI1001/5CW, PCI1005/5CW, PCI1004/5CW, PCI1003-I/5CW, PCI1001-I/5CW, PCI1005-I/5CW, PCI1004-I/5CW, PCI1003T/5CW, PCI1001T/5CW, PCI1005T/5CW, PCI1004T/5CW, PCI1003T-I/5CW, PCI1001T-I/5CW, PCI1005T-I/5CW, PCI1004T-I/5CW, PCI1008-I/5CW, PCI1008T-I/5CW, PCI1003-V/5CWVAO, PCI1004-V/5CWVAO, PCI1003T-V/5CWVAO and PCI1004T-V/5CWVAO catalog part numbers (CPN) available in 353L FCCSP (16x16mm) package.

### Pre and Post Summary Changes:

|  | Pre Change | Post Change | Change |
|--|------------|-------------|--------|
|--|------------|-------------|--------|

|                         |                                                           |                           |                                 |     |
|-------------------------|-----------------------------------------------------------|---------------------------|---------------------------------|-----|
| Assembly Site           | ASE Group Chung-Li (ASCL)                                 | ASE Group Chung-Li (ASCL) | STATS CHIPPAC KOREA LTD. (STAK) | Yes |
| Bumping Site            | ASE Group Chung-Li (ASCL)                                 | ASE Group Chung-Li (ASCL) | STATS CHIPPAC KOREA LTD. (STAK) | Yes |
| Substrate core material | HL832NSF(LCA)                                             | HL832NSF(LCA)             | DS7409HG ZSE                    | Yes |
| SM Material             | AUS SR1                                                   | AUS SR1                   | AUS SR1                         | No  |
| Bump Material           | Cu-pillar (Cu/SnAg)                                       | Cu-pillar (Cu/SnAg)       | Cu-pillar (Cu/SnAg)             | No  |
| Underfill Material      | UA28 (same as U8410-302)                                  | UA28 (same as U8410-302)  | U8410-302NP                     | Yes |
| Solder Ball Flux        | WF-6317                                                   | WF-6317                   | WF6317                          | No  |
| Chip Attach Material    | CIBS-239                                                  | CIBS-239                  | WF6317                          | Yes |
| Mold Compound           | KE-G1250LKDS                                              | KE-G1250LKDS              | KE-G2250SK                      | Yes |
| TIM Epoxy               | X-23-8112                                                 | X-23-8112                 | SE-4450                         | Yes |
| Packing Method - TRAY   | See Pre and Post Change Summary attachment for comparison |                           |                                 | Yes |

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve productivity and on-time delivery performance by qualifying STAK as an additional assembly site and bumping site.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** October 2026

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship

date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

|                          | October 2026 |    |    |    |    |
|--------------------------|--------------|----|----|----|----|
| Work Week                | 40           | 41 | 42 | 43 | 44 |
| Initial PCN Issue Date   |              | x  |    |    |    |
| Qual Report Availability |              |    |    |    | x  |
| Final PCN Issue Date     |              |    |    |    | x  |

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** October 08, 2026: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**[PCN\\_CENO-27KSCM101-Qual\\_Plan.pdf](#)**

**[PCN\\_CENO-27KSCM101-Pre and Post Change Summary.pdf](#)**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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